

IGBT Module

SK100GD126T

Preliminary Data

Features

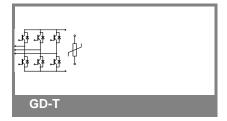
- One screw mounting module
- Fully compatible with SEMITOP®1,2,3
- Improved thermal performances by aluminium oxide substrate
- Trench IGBT technology
- CAL technology FWD
- Integrated NTC temperature sensor

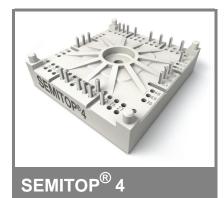
Typical Applications*

- Inverter up to 50 kVA
- Typ. motor power 22 kW

Absolute Maximum Ratings $T_s = 25 ^{\circ}\text{C}$, unless otherwise specified						
Symbol	Conditions			Values	Units	
IGBT					•	
V_{CES}	T _j = 25 °C			1200	V	
I _C	T _j = 150 °C	T _s = 25 °C		114	Α	
		$T_s = 70 ^{\circ}C$		86	Α	
I _{CRM}	I _{CRM} = 2 x I _{Cnom}			200	Α	
V_{GES}				± 20	V	
t _{psc}	V_{CC} = 600 V; $V_{GE} \le 20$ V; $V_{CES} < 1200$ V	T _j = 125 °C		10	μs	
Inverse D	Diode				•	
I _F	T _j = 150 °C	$T_s = 25 ^{\circ}C$		118	Α	
		$T_s = 70 ^{\circ}C$		88	Α	
I _{FRM}	I _{FRM} = 2 x I _{Fnom}			200	Α	
Module						
I _{t(RMS)}					Α	
T_{vj}				-40 + 150	°C	
T _{stg}				-40 +12 5	°C	
V _{isol}	AC, 1 min.			2500	V	

Characte	25 °C, unless otherwise specified					
Symbol	Conditions		min.	typ.	max.	Units
IGBT						•
$V_{GE(th)}$	$V_{GE} = V_{CE}$, $I_{C} = 4 \text{ mA}$		5	5,8	6,5	V
I _{CES}	$V_{GE} = 0 \text{ V}, V_{CE} = V_{CES}$	T _j = 25 °C			0,014	mA
		T _j = 125 °C				mA
I _{GES}	V _{CE} = 0 V, V _{GE} = 20 V	T _j = 25 °C			1200	nA
		T _j = 125 °C				nA
V _{CE0}		T _i = 25 °C		1	1,2	V
		T _j = 125 °C		0,9	1,1	V
r _{CE}	V _{GE} = 15 V	T _j = 25°C		7	9,5	mΩ
		T _j = 125°C		11	14	mΩ
V _{CE(sat)}	I _{Cnom} = 100 A, V _{GE} = 15 V	T _j = 25°C _{chiplev.}		1,7	2,15	V
		$T_j = 125^{\circ}C_{chiplev.}$		2,1	2,45	V
C _{ies}				7,2		nF
C _{oes}	$V_{CE} = 25, V_{GE} = 0 V$	f = 1 MHz		0,37		nF
C _{res}				0,32		nF
t _{d(on)}				115		ns
t _r	$R_{Gon} = 4 \Omega$	V _{CC} = 600V		28		ns
E _{on}	di/dt = 2250 A/µs	I _C = 100A		9,8		mJ
t _{d(off)}	$R_{Goff} = 4 \Omega$	T _j = 125 °C		509		ns
t _f	di/dt = 2250 A/µs	V _{GE} = -7/+15 V		100		ns
E _{off}				11,7		mJ
$R_{\text{th(j-s)}}$	per IGBT			0,4		K/W





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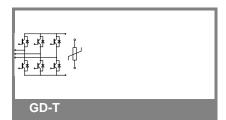
Typical Applications*

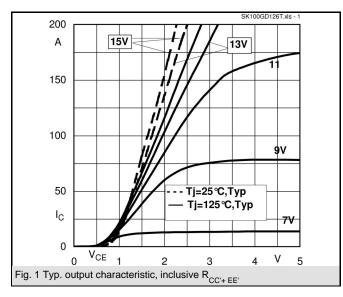
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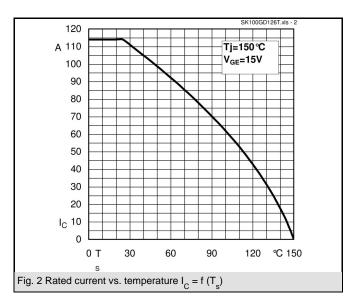
Characteristics							
Symbol	Conditions		min.	typ.	max.	Units	
Inverse Diode							
$V_F = V_{EC}$	I _{Fnom} = 100 A; V _{GE} = 0 V			1,5		V	
		$T_j = 125 ^{\circ}C_{\text{chiplev.}}$		1,5		V	
V _{F0}		T _j = 25 °C		1,18		V	
		T _j = 125 °C		1		V	
r _F		T _j = 25 °C		3,2		mΩ	
		T _j = 125 °C		5		$m\Omega$	
I _{RRM}	I _F = 100 A	T _i = 125 °C		100		Α	
Q_{rr}	di/dt = 2250 A/μs	,		20		μC	
E _{rr}	V _{CC} = 600V			7,3		mJ	
$R_{th(j-s)D}$	per diode			0,55		K/W	
M _s	to heat sink		2,5		2,75	Nm	
w				60		g	
Temperature sensor							
R ₁₀₀	$T_s = 100^{\circ}C (R_{25} = 5k\Omega)$			493±5%		Ω	

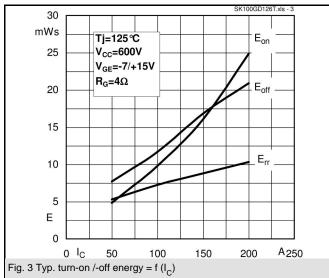
This is an electrostatic discharge sensitive device (ESDS), international standard IEC 60747-1, Chapter IX.

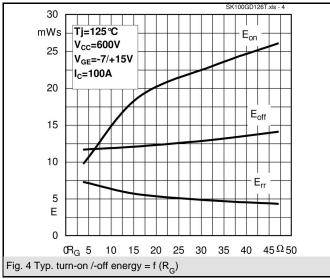
* The specifications of our components may not be considered as an assurance of component characteristics. Components have to be tested for the respective application. Adjustments may be necessary. The use of SEMIKRON products in life support appliances and systems is subject to prior specification and written approval by SEMIKRON. We therefore strongly recommend prior consultation of our personal.

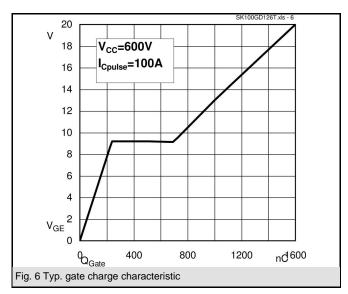


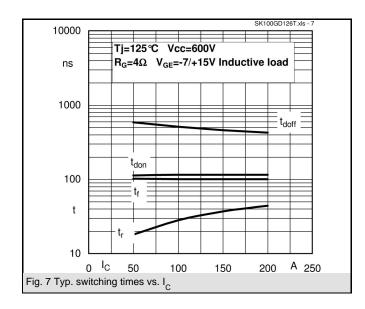


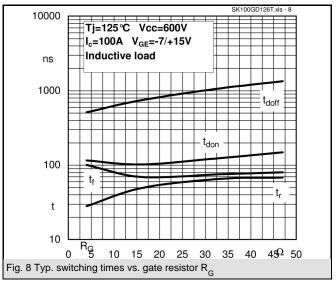


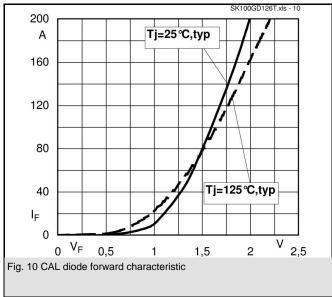


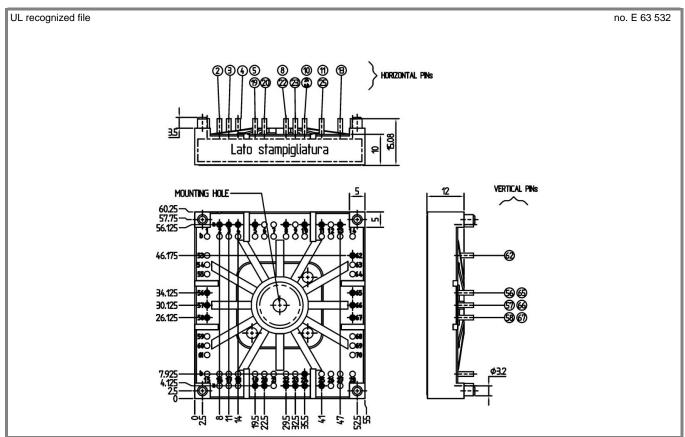












Case T74 (Suggested hole diameter for the solder pins in the circuit board: 2mm. Suggested hole diameter for the mounting pins in the circuit board: 3,6mm)

